

2022 45th International Spring Seminar on Electronics Technology (ISSE 2022)

**Vienna, Austria
11-15 May 2022**



**IEEE Catalog Number: CFP22509-POD
ISBN: 978-1-6654-6590-8**

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IEEE Catalog Number:	CFP22509-POD
ISBN (Print-On-Demand):	978-1-6654-6590-8
ISBN (Online):	978-1-6654-6589-2
ISSN:	2161-2528

Additional Copies of This Publication Are Available From:

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